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Guest Editorial

Special Issue on InterPACK 2018

The International Technical Conference on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK) is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics packaging and heterogeneous integration. Founded in 1992, InterPACK is the flagship conference for the American Society of Mechanical Engineers (ASME) Electronic and Photonic Packaging Division (EPPD). The InterPACK 2018 conference was held in San Francisco, CA, Aug. 27–30.

With nearly 185 technical papers and presentations, InterPACK 2018 reflected the changing landscape of electronics and photonics packaging as it pertains to the internet of things and efficient power delivery. Accordingly, the conference consisted of five technical tracks including: (1) heterogeneous integration: microsystems with diverse functionality, (2) servers of the future, internet of things, and edge to cloud, (3) structural and physical health monitoring, (4) power electronics, energy conversion, and storage, and (5) autonomous, hybrid, and electric vehicles.

This Special Issue of the ASME *Journal of Electronic Packaging* (JEP) was compiled based on recommendations from the peer review of the conference papers and from manuscripts submitted by authors of technical papers and presentations from the postconference open solicitation. All submitted manuscripts were subject to an independent peer-review process in accordance with the editorial standards of the ASME JEP. The accepted articles cover the topics of IT/data center design, electronics condition monitoring, light-emitting diode package design, device/package thermal management and reliability, and heat transfer with phase-change.

It is expected that this collection of papers will serve as a high quality, informative resource for EPPD members, as well as, the broader engineering community. We would like to sincerely thank all of the authors who contributed to this Special Issue and the reviewers who provided critical feedback for the enhancement of the final manuscripts. Kaustubh Nagarkar and Professor Y. C. Lee deserve further acknowledgment as the InterPACK 2018 General Conference Chair and the JEP editor, respectively.

We wish you the very best as you read through the JEP InterPACK 2018 Special Issue.

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